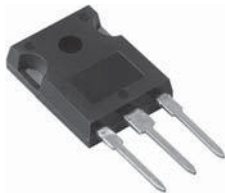
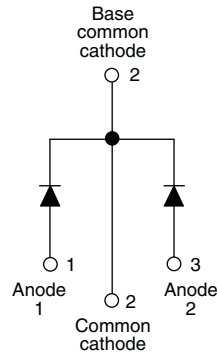


HEXFRED®

Ultrafast Soft Recovery Diode, 2 x 16 A


TO-247AC

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Compliant to RoHS Directive 2002/95/EC
- Designed and qualified for industrial level


RoHS
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA32PA120CPbF is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 16 A per leg continuous current, the VS-HFA32PA120CPbF is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA32PA120CPbF is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

Package	TO-247AC
$I_{F(AV)}$	2 x 16 A
V_R	1200 V
V_F at I_F	3.0 V
t_{rr} (typ.)	30 ns
T_J max.	150 °C
Diode variation	Single die

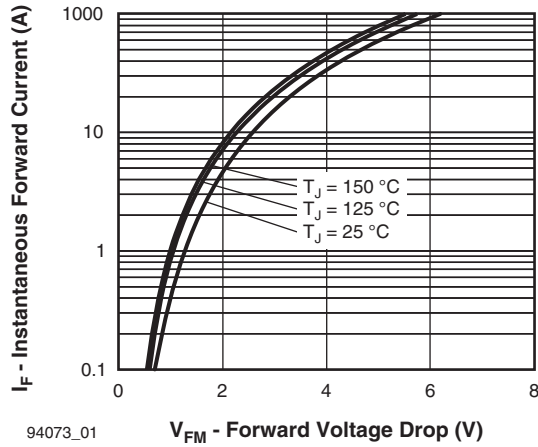
ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		1200	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	per leg	16
			per device	32
Single pulse forward current	I_{FSM}		190	A
Maximum repetitive forward current	I_{FRM}		64	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	151	°C
		$T_C = 100\text{ °C}$	60	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	W

ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	1200	-	-	V
Maximum forward voltage	V _{FM}	I _F = 16 A	-	2.5	3.0	
		I _F = 32 A	-	3.2	3.93	
		I _F = 16 A, T _J = 125 °C	-	2.3	2.7	
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	-	0.75	20	μA
		T _J = 125 °C, V _R = 0.8 x V _R rated	-	375	2000	
Junction capacitance	C _T	V _R = 200 V	-	27	40	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

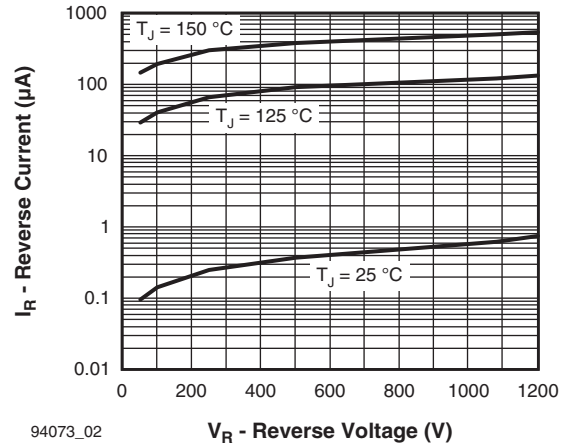
DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 10	t _{rr}	I _F = 1.0 A, di _F /dt = 200 A/μs, V _R = 30 V	-	30	-	ns
	t _{rr1}	T _J = 25 °C	-	90	135	
	t _{rr2}	T _J = 125 °C	-	164	245	
Peak recovery current See fig. 6	I _{RRM1}	T _J = 25 °C	-	5.8	10	A
	I _{RRM2}	T _J = 125 °C	-	8.3	15	
Reverse recovery charge See fig. 7	Q _{rr1}	T _J = 25 °C	-	260	675	nC
	Q _{rr2}	T _J = 125 °C	-	680	1838	
Peak rate of fall of recovery current during t _b See fig. 8	di _{(rec)M} /dt1	T _J = 25 °C	-	120	-	A/μs
	di _{(rec)M} /dt2	T _J = 125 °C	-	76	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	-	0.83	K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.50	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC (JEDEC)	HFA32PA120C			



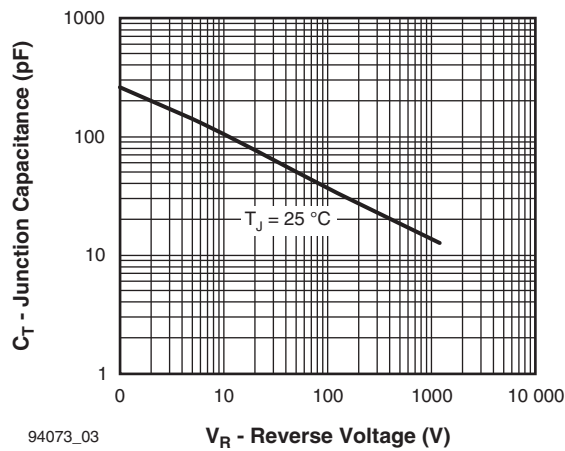
94073_01

Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current



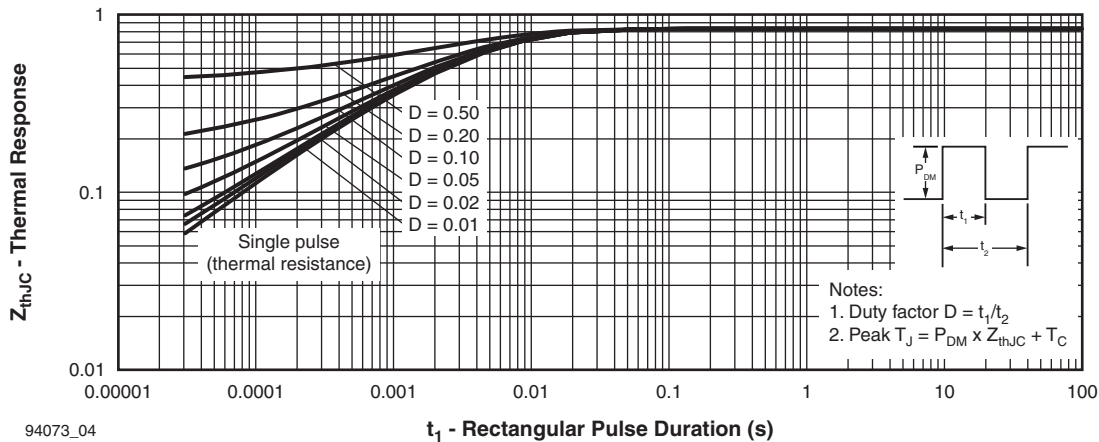
94073_02

Fig. 2 - Typical Reverse Current vs. Reverse Voltage



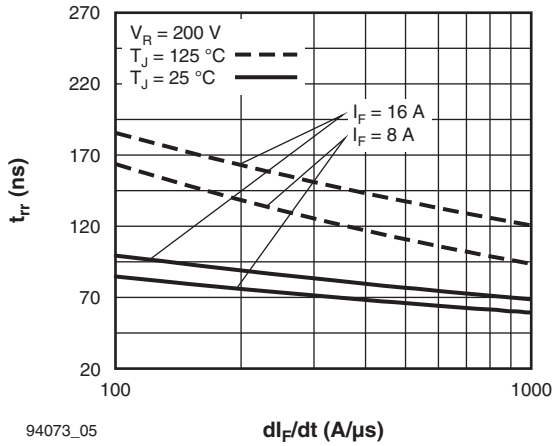
94073_03

Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage



94073_04

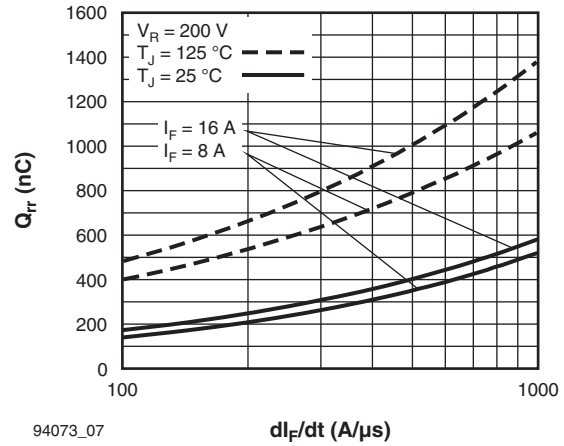
Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



94073_05

di_F/dt (A/ μ s)

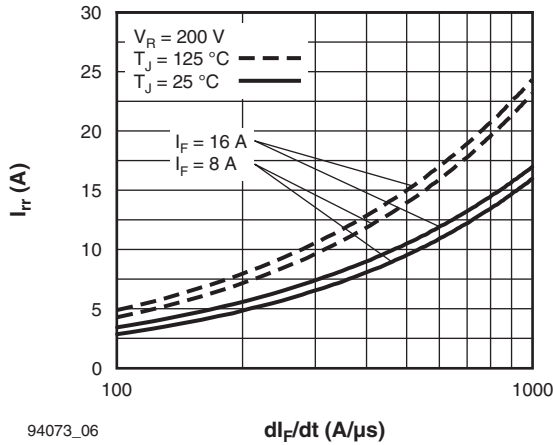
Fig. 5 - Typical Reverse Recovery Time vs. di_F/dt (Per Leg)



94073_07

di_F/dt (A/ μ s)

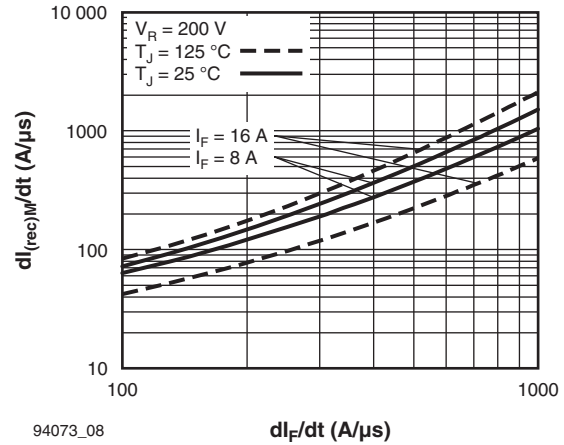
Fig. 7 - Typical Stored Charge vs. di_F/dt (Per Leg)



94073_06

di_F/dt (A/ μ s)

Fig. 6 - Typical Recovery Current vs. di_F/dt (Per Leg)



94073_08

di_F/dt (A/ μ s)

Fig. 8 - Typical $di_{(rec)M}/dt$ vs. di_F/dt (Per Leg)

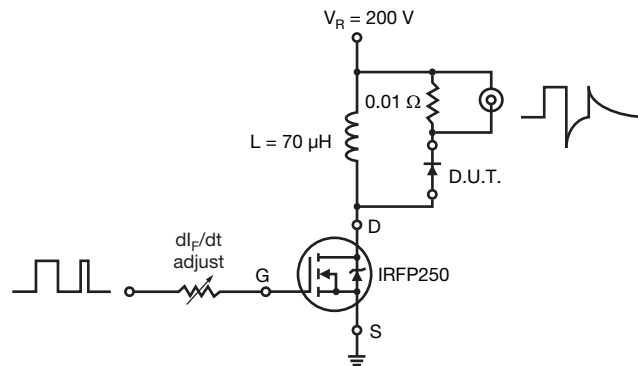


Fig. 9 - Reverse Recovery Parameter Test Circuit

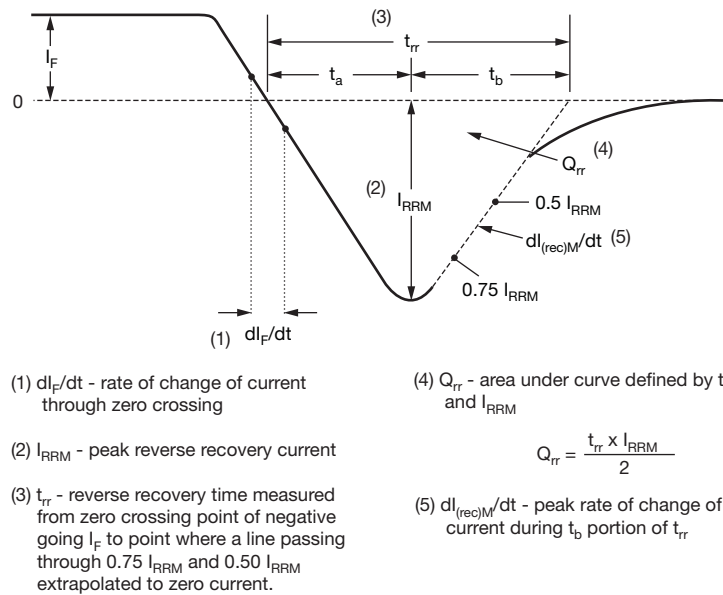


Fig. 10 - Reverse Recovery Waveform and Definitions

VS-HFA32PA120CPbF



Vishay Semiconductors

HEXFRED®
Ultrafast Soft Recovery Diode, 2 x 16 A

ORDERING INFORMATION TABLE

Device code	VS-	HF	A	32	PA	120	C	PbF
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (32 = 32 A)
- 5** - PA = TO-247AC
- 6** - Voltage rating: (120 = 1200 V)
- 7** - Circuit configuration
C = Common cathode
- 8** - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95223
Part marking information	www.vishay.com/doc?95226



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk and agree to fully indemnify and hold Vishay and its distributors harmless from and against any and all claims, liabilities, expenses and damages arising or resulting in connection with such use or sale, including attorneys fees, even if such claim alleges that Vishay or its distributor was negligent regarding the design or manufacture of the part. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.